This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of (laims

- 1. (Currently Amended). A method for modeling one or more predetermined characteristics of a semiconductor device comprising the steps:
 - a) fabricating a semiconductor device;
- b) measuring one or more predetermined physical characteristics of said semiconductor device;
- c) testing the semiconductor device; to establish a physically representative equivalent model of said one or more characteristics of said semiconductor device;
- d) varying one or more of said predetermined physical characteristics and fabricating a subsequent semiconductor device with said varied physical characteristics dimensions; and
- e) testing of the sample to establish a corrected physically representative model.
- 2. (Original). The method as recited in claim 1, further including the step of measuring the varied dimensions after said subsequent semiconductor is fabricated.
- 3. (Original). The method as recited in claim 1, wherein a scanning electron microscope (SEM) is used to measure said predetermined dimensions in step (b).
- 4. (Original). The method as recited in claim 1, wherein said testing in step (c) includes talling S-parameter measurements of said semiconductor device.
- 5. (Original). The method as recited in claim 1, wherein said one or more predetermined characteristics include device scaling; bias dependence; temperature dependence; lay out dependence and process dependence.
- 6. (Original). The method as recited in claim 1, wherein said one or more predetermined physical characteristics include the physical dimensions of the source access regions of aid semiconductor device.
- 7. (Original). The method as recited in claim 1, wherein said varied dimensions are measured by way of an SEM.
- 8. (Original). The method as recited in claim 1, wherein said corrected physically representative model is corrected based upon S-parameter measurements.

- 9. (Currently Amended). A process for making a semiconductor device comprising the steps of:
 - a) fabricating a semiconductor device;
- b) measuring one or more predetermined physical characteristics defining measured characteristics of said semiconductor device;
- c) testing said semiconductor device to establish a physically representative model;
- d) fabricating a subsequent semiconductor device in which said one or more measured characteristics are varied; defining varied characteristics.
 - e) measuring said varied characteristics; and
- f) testing said semiconductor device to establish a revised physically representative analytical model of said semiconductor device.
- 10. (Original). The process as recited in claim 9, further including step (g) repeating steps (d) through (f) one or more times.
- 11. (Original). The process as recited in claim 9, wherein said physically representative model in steps (c) and (b) is based on predetermined S-parameter measurements.
- 12. (Original). The process as recited in claim 9, wherein steps (b) and (c) include measurement by way of a scanning electron microscope.